IN THE CLAIMS

1. (Original) A method of reducing electromagnetic emissions from an electronic circuit, said electronic circuit comprising at least one electrical component and at least one grounding point, said method comprising:

applying a non-conductive coating over said electrical component; and

applying a conductive coating over said non-conductive coating and in contact with said grounding point so as to ground said conductive coating and thereby reduce electromagnetic emissions from said electronic circuit.

2. (Currently amended) The method of claim 1, ~~wherein a hole is formed in said non-conductive coating above said grounding point so as to enable contact between said conductive coating and said grounding point~~ further comprising, prior to applying the conductive coating, opening a hole in the non-conductive coating above the at least one grounding point to enable contact between the conductive coating and the at least one grounding point.

3. (Currently amended) The method of claim 1, ~~wherein said grounding point is located proximate an edge of said electronic circuit, and wherein said non-conductive coating does not coat said edge of said electronic circuit so as to enable contact between said conductive coating and said grounding point~~ wherein applying the non-conductive coating comprises applying the non-conductive coating on a central portion of the electronic circuit where the at least one electrical component is disposed but not on an edge portion of the electronic circuit where the at least one grounding point is disposed; and

wherein applying the conductive coating comprises applying the conductive coating on the central portion of the electronic circuit to contact the non-conductive coating and applying the conductive coating on the edge portion of the electronic circuit to contact the at least one grounding point.

4. (Currently amended) The method of claim 1, wherein ~~said non-conductive coating conforms to said electrical component, and wherein said conductive coating conforms to said non-conductive coating and said grounding point~~ applying the non-conductive coating comprises conforming the non-conductive coating to a top surface of the at least one electrical component, and wherein applying the conductive coating comprises conforming the conductive coating to a top surface of the non-conductive coating and to a top surface of the grounding point.

5. (Currently amended) ~~An electronic circuit comprising at least one electrical component and at least one grounding point, wherein a non-conductive coating is applied over said electrical component, and wherein a conductive coating is applied over said non-conductive coating and in contact with said grounding point so as to ground said conductive coating~~

An electronic circuit comprising:

at least one electrical component;

at least one grounding pad;

a non-conductive coating disposed over the at least one electrical component; and

a conductive coating disposed on the non-conductive coating and on the at least one grounding pad, the conductive coating contiguous with at least a portion of the at least one grounding pad.

6. (Currently amended) The electronic circuit of claim 5, ~~wherein a hole is formed in said non-conductive coating above said grounding point so as to enable contact between said conductive coating and said grounding point~~ the non-conductive coating having an opening disposed above the portion of the at least one grounding pad, the conductive coating physically touching the portion of the at least one grounding pad through the opening.

7. (Currently amended) The electronic circuit of claim 5, ~~wherein said grounding point is located proximate an edge of said electronic circuit, and wherein said non-~~

~~conductive coating does not coat said edge of said electronic circuit so as to enable contact between said conductive coating and said grounding point~~ the electronic circuit having a central region and a peripheral region, a boundary between the central region and the peripheral region defined by an outermost edge of the non-conductive coating, the at least one grounding pad disposed at least partially within the peripheral region.

8. (Currently amended) The electronic circuit of claim 5, ~~wherein said non-conductive coating conforms to said electrical component, and wherein said conductive coating conforms to said non-conductive coating and said grounding point~~ the non-conductive coating conforming to an upper surface of the at least one electrical component, the conductive coating conforming to an upper surface of the non-conductive coating and an upper surface of the at least one grounding pad.

9. (Currently amended) The electronic circuit of ~~claim 5,~~ claim 8, wherein ~~said~~ the non-conductive coating comprises a ~~conformal coating~~ material selected from the ~~following group:~~ group consisting of insulating tape, rubber, silicone, room-temperature vulcanizing silicone rubber, ~~plastic,~~ insulating varnish, and combinations thereof.

10. (Currently amended) The electronic circuit of ~~claim 5,~~ claim 8, wherein ~~said~~ the conductive coating comprises a ~~conformal coating~~ material selected from the ~~following group: conductive tape,~~ group consisting of conductive paint, silver paint, and combinations thereof.

11. (Cancelled)

12. (New) The electronic circuit of claim 7, the at least one grounding pad disposed entirely within the peripheral region.

13. (New) The method of claim 1, wherein applying the non-conductive coating over the electrical component comprises applying the non-conductive coating to a top surface

of the electrical component, wherein applying the conductive coating over the non-conductive coating and in contact with the grounding point comprises applying the conductive coating to a top surface of the non-conductive coating and to a top surface of the grounding point, and wherein applying the conductive coating occurs after applying the non-conductive coating.

14. (New) The method of claim 1, wherein applying the non-conductive coating comprises applying the non-conductive coating such that the non-conductive coating exposes at least a portion of an upper surface of the at least one grounding point.

15. (New) The method of claim 1, wherein applying the conductive coating comprises applying the conductive coating such that the conductive coating is contiguous with at least a portion of the at least one grounding point.

16. (New) A device comprising:

a circuit board having a peripheral region and a central region;

electrical components disposed within the central region of the circuit board;

at least one grounding pad disposed within the peripheral region of the circuit board;

a non-conductive coating disposed on at least one of the electrical components; and

a conductive coating disposed on the non-conductive coating and disposed on the at least one grounding pad, the conductive coating contiguous with at least a first portion of an upper surface of the at least one grounding pad.

17. (New) The device of claim 16, wherein the peripheral region surrounds the central region.

18. (New) The device of claim 17, wherein the non-conductive coating is contiguous with a second portion of the upper surface of the at least one grounding pad, the first

portion and the second portion constituting an entirety of the upper surface of the at least one grounding pad.

19. (New) The device of claim 17, wherein the non-conductive coating is disposed on a first portion of the central region, the first portion less than an entirety of the central region.